



MJ N-Channel Enhancement Mode Power MOSFET

Description

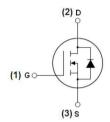
The MJ2012 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

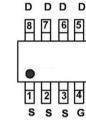
General Features

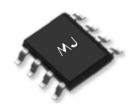
- ♦ V_{DS} =20V,I_D =12A R_{DS(ON)} <8mΩ @ V_{GS}=10V R_{DS(ON)} <11mΩ @ V_{GS}=10V
- ◆ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current

Application

- ◆ DC/DC Converter
- ◆ Notebook Vcore







Schematic diagram

Marking and pin assignment

SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2012	MJ2012	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	12	А
Drain Current-Continuous(T₄ =100°C)	ID(100°C)	8	А
Pulsed Drain Current	Ідм	40	А
Maximum Power Dissipation	Po	2.5	W
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	Reja	50	°C/W
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Electrical Characteristics (T_A=25℃ unless otherwise noted)

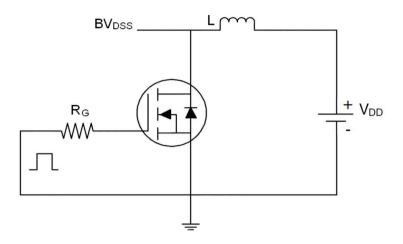
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V,I _D =250µA	20	-	-	V
Zero Gate Voltage Drain Current	loss	Vps=30V,Vgs=0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	lgss Vps=±20V,Vps=0V		-	±100	nA
On Characteristics (Note 3)	,					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	0.5	0.8	1.2	V
B : 0 0 0 1 1 B : 1		V _{GS} =4.5V, I _D =6A	-	6	8	mΩ
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =2.5V, I _D =5A	-	8	11	mΩ
Forward Transconductance	grs	V _{DS} =10V,I _D =6A	20	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	Clss		-	2000	-	PF
Output Capacitance	Coss	V _{DS} =10V,V _{GS} =0V F=1.0MHz	-	402	-	PF
Reverse Transfer Capacitance	Crss		-	170	-	PF
Switching Characteristics (Note 4)	,					
Turn-on Delay Time	t _{d(on)}		-	25	-	nS
Turn-on Rise Time	tr	VDD=10V,ID=6A	-	15	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =4. 5V,R _{GEN} =1Ω	-	25	-	nS
Turn-Off Fall Time	tr		-	15	-	nS
Total Gate Charge	Qg		-	42	-	nC
Gate-Source Charge	Qgs	V _{DS} =10V,I _D =6A V _{GS} =10V	-	10.8	-	nC
Gate-Drain Charge	Qgd		-	9.2	-	nC
Drain-Source Diode Characteristics	1	1	1	1		
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =6A	-	-	1.2	V
Diode Forward Current (Note 2)	ls		_	-	12	А

Notes

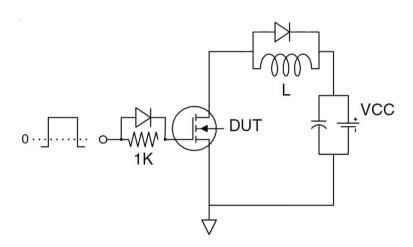
- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3 Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4 Guaranteed by design, not subject to production



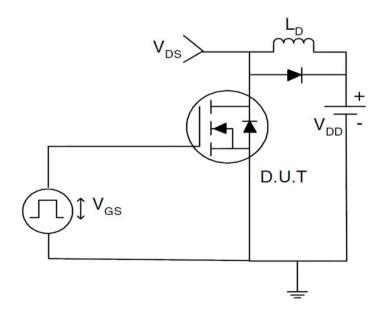




Eas test Circuit



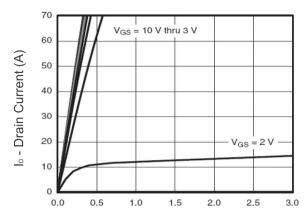
Gate charge test Circuit



Switch Time Test Circuit



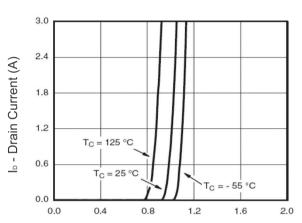
Typical Electrical and Thermal Characteristics (Curves)



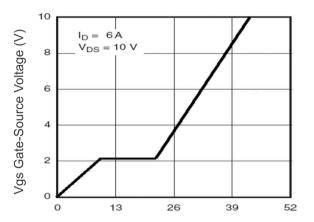
1.7 V_{GS} = 4.5 V I_D = 6A 1.3 1.3 1.3 0.9 0.7 -50 -25 0 25 50 75 100 125 150

Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics

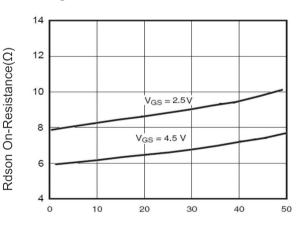


TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature

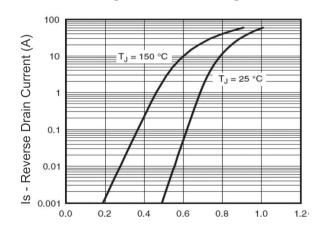


Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

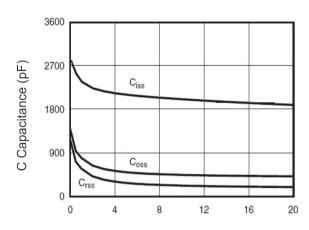


I_D - Drain Current (A)

Figure 3 Rdson- Drain Current

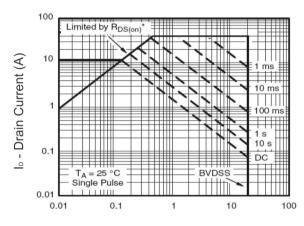
Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward





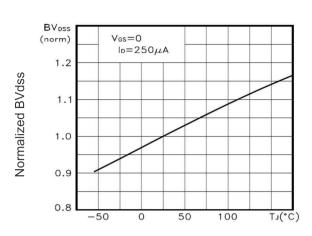
Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds



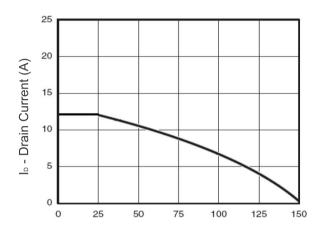
Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area



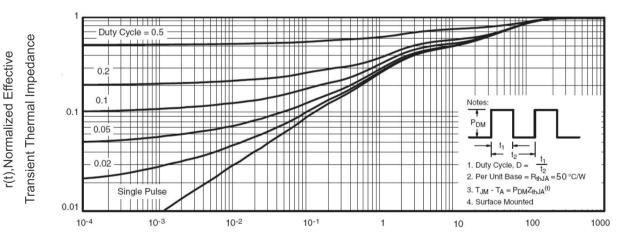
T_J -Junction Temperature(°C)

Figure 9 BV_{DSS} vs Junction Temperature



T_J -Junction Temperature(°C)

Figure 10 Current vs Junction Temperature



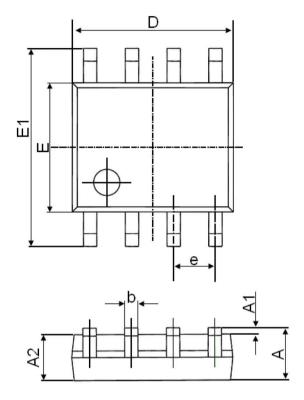
Square Wave Pluse Duration(sec)

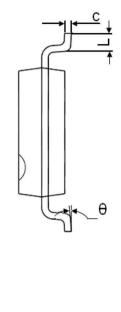
Figure 11 Normalized Maximum Transient Thermal Impedance





SOP-8 Package Information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050(BSC)		
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	





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